

MC10EP05, MC100EP05

3.3V / 5V ECL 2-Input Differential AND/NAND

Description

The MC10/100EP05 is a 2-input differential AND/NAND gate. The device is functionally equivalent to the EL05 and LVEL05 devices. With AC performance much faster than the LVEL05 device, the EP05 is ideal for applications requiring the fastest AC performance available.

The 100 Series contains temperature compensation.

Features

- 220 ps Typical Propagation Delay
- Maximum Frequency > 3 GHz Typical
- PECL Mode Operating Range: $V_{CC} = 3.0\text{ V}$ to 5.5 V with $V_{EE} = 0\text{ V}$
- NECL Mode Operating Range: $V_{CC} = 0\text{ V}$ with $V_{EE} = -3.0\text{ V}$ to -5.5 V
- Open Input Default State
- Safety Clamp on Inputs
- Q Output Will Default LOW with Inputs Open or at V_{EE}
- Pb-Free Packages are Available

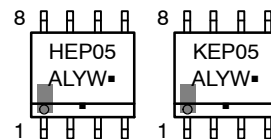


ON Semiconductor®

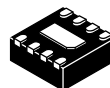
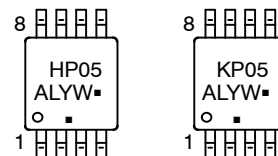
MARKING DIAGRAMS*



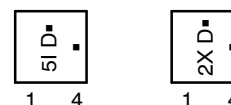
SOIC-8
D SUFFIX
CASE 751



TSSOP-8
DT SUFFIX
CASE 948R



DFN8
MN SUFFIX
CASE 506AA



H = MC10	A = Assembly Location
K = MC100	L = Wafer Lot
5I = MC10	Y = Year
2X = MC100	W = Work Week
D = Date Code	▪ = Pb-Free Package

(Note: Microdot may be in either location)

*For additional marking information, refer to Application Note AND8002/D.

ORDERING INFORMATION

See detailed ordering and shipping information in the package dimensions section on page 8 of this data sheet.

MC10EP05, MC100EP05

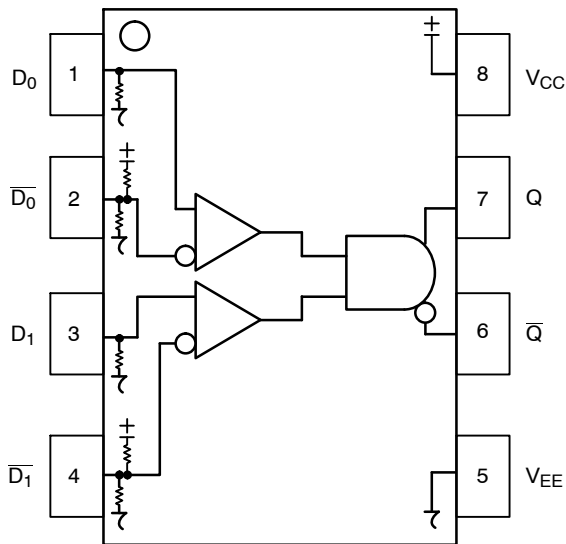


Figure 1. 8-Lead Pinout (Top View) and Logic Diagram

Table 1. PIN DESCRIPTION

Pin	Function
D0*, D1*, $\overline{D0}$ **, $\overline{D1}$ **	ECL Data Inputs
Q, \overline{Q}	ECL Data Outputs
V _{CC}	Positive Supply
V _{EE}	Negative Supply
EP	(DFN8 only) Thermal exposed pad must be connected to a sufficient thermal conduit. Electrically connect to the most negative supply (GND) or leave unconnected, floating open.

* Pins will default LOW when left open.

** Pins will default to $V_{CC}/2$ when left open.

Table 2. TRUTH TABLE

D0	D1	$\overline{D0}$	$\overline{D1}$	Q	\overline{Q}
L	L	H	H	L	H
L	H	H	L	L	H
H	L	L	H	L	H
H	H	L	L	H	L

Table 3. ATTRIBUTES

Characteristics		Value	
Internal Input Pulldown Resistor		75 k Ω	
Internal Input Pullup Resistor		37.5 k Ω	
ESD Protection	Human Body Model	> 4 kV	
	Machine Model	> 200 V	
	Charged Device Model	> 2 kV	
Moisture Sensitivity, Indefinite Time Out of Drypack (Note 1)		Pb Pkg	Pb-Free Pkg
	SOIC-8	Level 1	Level 1
	TSSOP-8 DFN8	Level 1	Level 3 Level 1
Flammability Rating	Oxygen Index: 28 to 34	UL 94 V-0 @ 0.125 in	
Transistor Count	137 Devices		
Meets or exceeds JEDEC Spec EIA/JESD78 IC Latchup Test			

1. For additional information, see Application Note AND8003/D.

MC10EP05, MC100EP05

Table 4. MAXIMUM RATINGS

Symbol	Parameter	Condition 1	Condition 2	Rating	Unit
V _{CC}	PECL Mode Power Supply	V _{EE} = 0 V		6	V
V _{EE}	NECL Mode Power Supply	V _{CC} = 0 V		-6	V
V _I	PECL Mode Input Voltage	V _{EE} = 0 V	V _I ≤ V _{CC}	6	V
	NECL Mode Input Voltage	V _{CC} = 0 V	V _I ≥ V _{EE}	-6	V
I _{out}	Output Current	Continuous Surge		50	mA
				100	mA
T _A	Operating Temperature Range			-40 to +85	°C
T _{stg}	Storage Temperature Range			-65 to +150	°C
θ _{JA}	Thermal Resistance (Junction-to-Ambient)	0 lfpm	SOIC-8	190	°C/W
		500 lfpm	SOIC-8	130	°C/W
θ _{JC}	Thermal Resistance (Junction-to-Case)	Standard Board	SOIC-8	41 to 44	°C/W
θ _{JA}	Thermal Resistance (Junction-to-Ambient)	0 lfpm 500 lfpm	TSSOP-8	185	°C/W
			TSSOP-8	140	°C/W
θ _{JC}	Thermal Resistance (Junction-to-Case)	Standard Board	TSSOP-8	41 to 44	°C/W
θ _{JA}	Thermal Resistance (Junction-to-Ambient)	0 lfpm 500 lfpm	DFN8	129	°C/W
			DFN8	84	°C/W
T _{sol}	Wave Solder	Pb Pb-Free	<2 to 3 sec @ 248°C <2 to 3 sec @ 260°C	265 265	°C
θ _{JC}	Thermal Resistance (Junction-to-Case)	(Note 2)	DFN8	35 to 40	°C/W

Stresses exceeding Maximum Ratings may damage the device. Maximum Ratings are stress ratings only. Functional operation above the Recommended Operating Conditions is not implied. Extended exposure to stresses above the Recommended Operating Conditions may affect device reliability.

2. JEDEC standard multilayer board – 2S2P (2 signal, 2 power)

Table 5. 10EP DC CHARACTERISTICS, PECL V_{CC} = 3.3 V, V_{EE} = 0 V (Note 3)

Symbol	Characteristic	-40°C			25°C			85°C			Unit
		Min	Typ	Max	Min	Typ	Max	Min	Typ	Max	
I _{EE}	Power Supply Current	20	24	29	20	24	29	20	24	29	mA
V _{OH}	Output HIGH Voltage (Note 4)	2165	2290	2415	2230	2355	2480	2290	2415	2540	mV
V _{OL}	Output LOW Voltage (Note 4)	1365	1490	1615	1430	1555	1680	1490	1615	1740	mV
V _{IH}	Input HIGH Voltage (Single-Ended)	2090		2415	2155		2480	2215		2540	mV
V _{IL}	Input LOW Voltage (Single-Ended)	1365		1690	1460		1755	1490		1815	mV
V _{IHCMR}	Input HIGH Voltage Common Mode Range (Differential Configuration) (Note 5)	2.0		3.3	2.0		3.3	2.0		3.3	V
I _{IH}	Input HIGH Current			150			150			150	μA
I _{IL}	Input LOW Current	D	0.5		0.5			0.5			μA
		\bar{D}	-150		-150			-150			

NOTE: Device will meet the specifications after thermal equilibrium has been established when mounted in a test socket or printed circuit board with maintained transverse airflow greater than 500 lfpm. Electrical parameters are guaranteed only over the declared operating temperature range. Functional operation of the device exceeding these conditions is not implied. Device specification limit values are applied individually under normal operating conditions and not valid simultaneously.

3. Input and output parameters vary 1:1 with V_{CC}. V_{EE} can vary +0.3 V to -2.2 V.

4. All loading with 50 Ω to V_{CC} - 2.0 V.

5. V_{IHCMR} min varies 1:1 with V_{EE}, V_{IHCMR} max varies 1:1 with V_{CC}. The V_{IHCMR} range is referenced to the most positive side of the differential input signal.

MC10EP05, MC100EP05

Table 8. 100EP DC CHARACTERISTICS, PECL $V_{CC} = 3.3\text{ V}$, $V_{EE} = 0\text{ V}$ (Note 12)

Symbol	Characteristic	-40°C			25°C			85°C			Unit
		Min	Typ	Max	Min	Typ	Max	Min	Typ	Max	
I_{EE}	Power Supply Current	15	25	32	17	27	36	19	28	38	mA
V_{OH}	Output HIGH Voltage (Note 13)	2155	2280	2405	2155	2280	2405	2155	2280	2405	mV
V_{OL}	Output LOW Voltage (Note 13)	1355	1480	1605	1355	1480	1605	1355	1480	1605	mV
V_{IH}	Input HIGH Voltage (Single-Ended)	2075		2420	2075		2420	2075		2420	mV
V_{IL}	Input LOW Voltage (Single-Ended)	1355		1675	1355		1675	1355		1675	mV
V_{IHCMR}	Input HIGH Voltage Common Mode Range (Differential Configuration) (Note 14)	2.0		3.3	2.0		3.3	2.0		3.3	V
I_{IH}	Input HIGH Current			150			150			150	μA
I_{IL}	Input LOW Current	D \bar{D}	0.5 -150		0.5 -150			0.5 -150			μA

NOTE: Device will meet the specifications after thermal equilibrium has been established when mounted in a test socket or printed circuit board with maintained transverse airflow greater than 500 lfm. Electrical parameters are guaranteed only over the declared operating temperature range. Functional operation of the device exceeding these conditions is not implied. Device specification limit values are applied individually under normal operating conditions and not valid simultaneously.

12. Input and output parameters vary 1:1 with V_{CC} . V_{EE} can vary +0.3 V to -2.2 V.

13. All loading with $50\ \Omega$ to $V_{CC} - 2.0\text{ V}$.

14. V_{IHCMR} min varies 1:1 with V_{EE} . V_{IHCMR} max varies 1:1 with V_{CC} . The V_{IHCMR} range is referenced to the most positive side of the differential input signal.

Table 9. 100EP DC CHARACTERISTICS, PECL $V_{CC} = 5.0\text{ V}$, $V_{EE} = 0\text{ V}$ (Note 15)

Symbol	Characteristic	-40°C			25°C			85°C			Unit
		Min	Typ	Max	Min	Typ	Max	Min	Typ	Max	
I_{EE}	Power Supply Current	15	25	32	17	27	36	19	28	38	mA
V_{OH}	Output HIGH Voltage (Note 16)	3855	3980	4105	3855	3980	4105	3855	3980	4105	mV
V_{OL}	Output LOW Voltage (Note 16)	3055	3180	3305	3055	3180	3305	3055	3180	3305	mV
V_{IH}	Input HIGH Voltage (Single-Ended)	3775		4120	3775		4120	3775		4120	mV
V_{IL}	Input LOW Voltage (Single-Ended)	3055		3375	3055		3375	3055		3375	mV
V_{IHCMR}	Input HIGH Voltage Common Mode Range (Differential Configuration) (Note 17)	2.0		5.0	2.0		5.0	2.0		5.0	V
I_{IH}	Input HIGH Current			150			150			150	μA
I_{IL}	Input LOW Current	D \bar{D}	0.5 -150		0.5 -150			0.5 -150			μA

NOTE: Device will meet the specifications after thermal equilibrium has been established when mounted in a test socket or printed circuit board with maintained transverse airflow greater than 500 lfm. Electrical parameters are guaranteed only over the declared operating temperature range. Functional operation of the device exceeding these conditions is not implied. Device specification limit values are applied individually under normal operating conditions and not valid simultaneously.

15. Input and output parameters vary 1:1 with V_{CC} . V_{EE} can vary +2.0 V to -0.5 V.

16. All loading with $50\ \Omega$ to $V_{CC} - 2.0\text{ V}$.

17. V_{IHCMR} min varies 1:1 with V_{EE} . V_{IHCMR} max varies 1:1 with V_{CC} . The V_{IHCMR} range is referenced to the most positive side of the differential input signal.

MC10EP05, MC100EP05

Table 10. 100EP DC CHARACTERISTICS, NECL $V_{CC} = 0\text{ V}$, $V_{EE} = -5.5\text{ V to } -3.0\text{ V}$ (Note 18)

Symbol	Characteristic	-40°C			25°C			85°C			Unit
		Min	Typ	Max	Min	Typ	Max	Min	Typ	Max	
I_{EE}	Power Supply Current	15	25	32	17	27	36	19	28	38	mA
V_{OH}	Output HIGH Voltage (Note 19)	-1145	-1020	-895	-1145	-1020	-895	-1145	-1020	-895	mV
V_{OL}	Output LOW Voltage (Note 19)	-1945	-1820	-1695	-1945	-1820	-1695	-1945	-1820	-1695	mV
V_{IH}	Input HIGH Voltage (Single-Ended)	-1225		-880	-1225		-880	-1225		-880	mV
V_{IL}	Input LOW Voltage (Single-Ended)	-1945		-1625	-1945		-1625	-1945		-1625	mV
V_{IHCMR}	Input HIGH Voltage Common Mode Range (Differential Configuration) (Note 20)	$V_{EE}+2.0$		0.0	$V_{EE}+2.0$		0.0	$V_{EE}+2.0$		0.0	V
I_{IH}	Input HIGH Current			150			150			150	μA
I_{IL}	Input LOW Current	D D	0.5 -150		0.5 -150			0.5 -150			μA

NOTE: Device will meet the specifications after thermal equilibrium has been established when mounted in a test socket or printed circuit board with maintained transverse airflow greater than 500 lfpm. Electrical parameters are guaranteed only over the declared operating temperature range. Functional operation of the device exceeding these conditions is not implied. Device specification limit values are applied individually under normal operating conditions and not valid simultaneously.

18. Input and output parameters vary 1:1 with V_{CC} .

19. All loading with $50\ \Omega$ to $V_{CC} - 2.0\text{ V}$.

20. V_{IHCMR} min varies 1:1 with V_{EE} ; V_{IHCMR} max varies 1:1 with V_{CC} . The V_{IHCMR} range is referenced to the most positive side of the differential input signal.

Table 11. AC CHARACTERISTICS $V_{CC} = 0\text{ V}$; $V_{EE} = -3.0\text{ V to } -5.5\text{ V}$ or $V_{CC} = 3.0\text{ V to } 5.5\text{ V}$; $V_{EE} = 0\text{ V}$ (Note 21)

Symbol	Characteristic	-40°C			25°C			85°C			Unit	
		Min	Typ	Max	Min	Typ	Max	Min	Typ	Max		
f_{max}	Maximum Frequency (Figure 2)		> 3			> 3			> 3		GHz	
t_{PLH} , t_{PHL}	Propagation Delay to Output Differential	160	210	260	170	220	270	210	260	320	ps	
t_{JITTER}	Random Clock Jitter (Figure 2)		0.2	< 1		0.2	< 1		0.2	1.5	ps	
V_{PP}	Input Voltage Swing (Differential Configuration)	150	800	1200	150	800	1200	150	800	1200	mV	
t_r t_f	Output Rise/Fall Times (20% – 80%)	Q	70	120	170	80	130	180	100	150	200	ps

NOTE: Device will meet the specifications after thermal equilibrium has been established when mounted in a test socket or printed circuit board with maintained transverse airflow greater than 500 lfpm. Electrical parameters are guaranteed only over the declared operating temperature range. Functional operation of the device exceeding these conditions is not implied. Device specification limit values are applied individually under normal operating conditions and not valid simultaneously.

21. Measured using a 750 mV source, 50% duty cycle clock source. All loading with $50\ \Omega$ to $V_{CC} - 2.0\text{ V}$.

MC10EP05, MC100EP05

ORDERING INFORMATION

Device	Package	Shipping [†]
MC10EP05D	SOIC-8	98 Units / Rail
MC10EP05DG	SOIC-8 (Pb-Free)	98 Units / Rail
MC10EP05DR2	SOIC-8	2500 / Tape & Reel
MC10EP05DR2G	SOIC-8 (Pb-Free)	2500 / Tape & Reel
MC10EP05DT	TSSOP-8	100 Units / Rail
MC10EP05DTG	TSSOP-8 (Pb-Free)	100 Units / Rail
MC10EP05DTR2	TSSOP-8	2500 / Tape & Reel
MC10EP05DTR2G	TSSOP-8 (Pb-Free)	2500 / Tape & Reel
MC10EP05MNR4	DFN8	1000 / Tape & Reel
MC10EP05MNR4G	DFN8 (Pb-Free)	1000 / Tape & Reel
MC100EP05D	SOIC-8	98 Units / Rail
MC100EP05DG	SOIC-8 (Pb-Free)	98 Units / Rail
MC100EP05DR2	SOIC-8	2500 / Tape & Reel
MC100EP05DR2G	SOIC-8 (Pb-Free)	2500 / Tape & Reel
MC100EP05DT	TSSOP-8	100 Units / Rail
MC100EP05DTG	TSSOP-8 (Pb-Free)	100 Units / Rail
MC100EP05DTR2	TSSOP-8	2500 / Tape & Reel
MC100EP05DTR2G	TSSOP-8 (Pb-Free)	2500 / Tape & Reel
MC100EP05MNR4	DFN8	1000 / Tape & Reel
MC100EP05MNR4G	DFN8 (Pb-Free)	1000 / Tape & Reel

[†]For information on tape and reel specifications, including part orientation and tape sizes, please refer to our Tape and Reel Packaging Specifications Brochure, BRD8011/D.

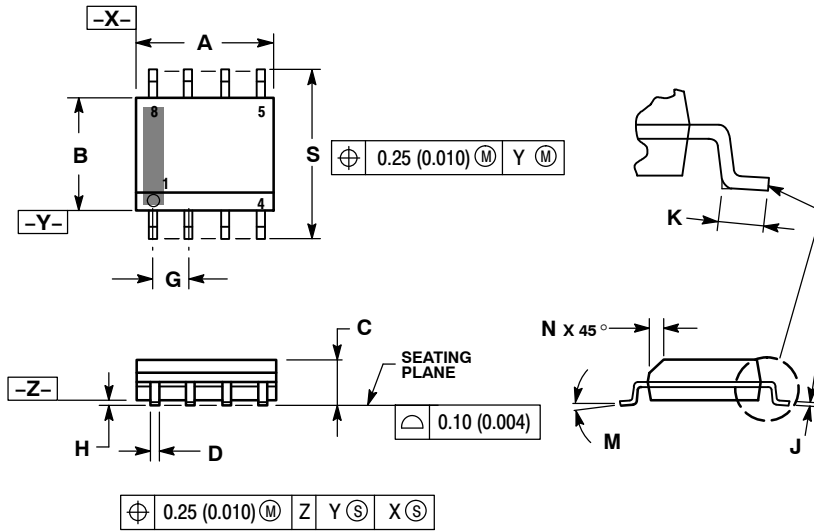
Resource Reference of Application Notes

- AN1405/D** – ECL Clock Distribution Techniques
- AN1406/D** – Designing with PECL (ECL at +5.0 V)
- AN1503/D** – ECLinPS™ I/O SPICE Modeling Kit
- AN1504/D** – Metastability and the ECLinPS Family
- AN1568/D** – Interfacing Between LVDS and ECL
- AN1672/D** – The ECL Translator Guide
- AND8001/D** – Odd Number Counters Design
- AND8002/D** – Marking and Date Codes
- AND8020/D** – Termination of ECL Logic Devices
- AND8066/D** – Interfacing with ECLinPS
- AND8090/D** – AC Characteristics of ECL Devices

MC10EP05, MC100EP05

PACKAGE DIMENSIONS

SOIC-8 NB
CASE 751-07
ISSUE AH

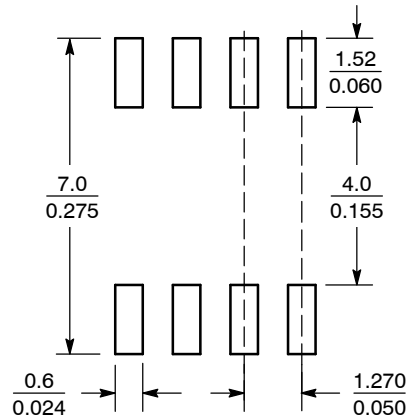


NOTES:

1. DIMENSIONING AND TOLERANCING PER ANSI Y14.5M, 1982.
2. CONTROLLING DIMENSION: MILLIMETER.
3. DIMENSION A AND B DO NOT INCLUDE MOLD PROTRUSION.
4. MAXIMUM MOLD PROTRUSION 0.15 (0.006) PER SIDE.
5. DIMENSION D DOES NOT INCLUDE DAMBAR PROTRUSION. ALLOWABLE DAMBAR PROTRUSION SHALL BE 0.127 (0.005) TOTAL IN EXCESS OF THE D DIMENSION AT MAXIMUM MATERIAL CONDITION.
6. 751-01 THRU 751-06 ARE OBSOLETE. NEW STANDARD IS 751-07.

DIM	MILLIMETERS		INCHES	
	MIN	MAX	MIN	MAX
A	4.80	5.00	0.189	0.197
B	3.80	4.00	0.150	0.157
C	1.35	1.75	0.053	0.069
D	0.33	0.51	0.013	0.020
G	1.27 BSC		0.050 BSC	
H	0.10	0.25	0.004	0.010
J	0.19	0.25	0.007	0.010
K	0.40	1.27	0.016	0.050
M	0°	8°	0°	8°
N	0.25	0.50	0.010	0.020
S	5.80	6.20	0.228	0.244

SOLDERING FOOTPRINT*



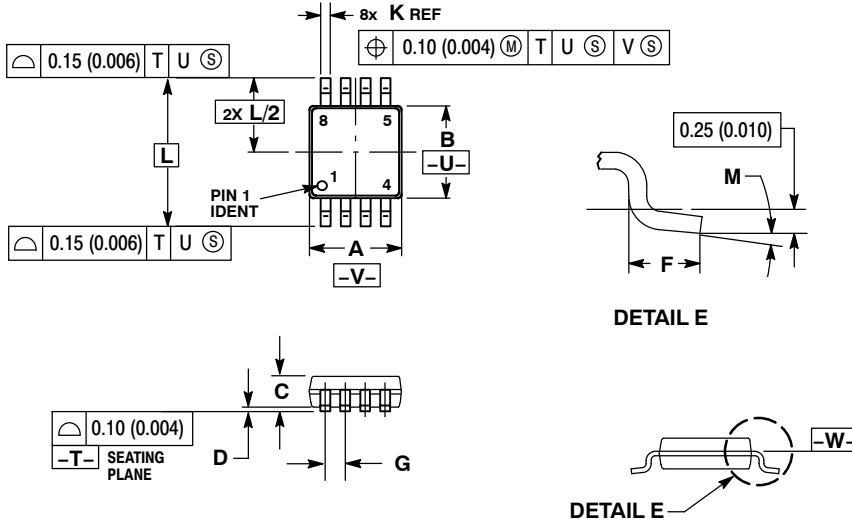
SCALE 6:1 (mm/inches)

*For additional information on our Pb-Free strategy and soldering details, please download the ON Semiconductor Soldering and Mounting Techniques Reference Manual, SOLDERRM/D.

MC10EP05, MC100EP05

PACKAGE DIMENSIONS

TSSOP-8
DT SUFFIX
PLASTIC TSSOP PACKAGE
CASE 948R-02
ISSUE A



NOTES:

1. DIMENSIONING AND TOLERANCING PER ANSI Y14.5M, 1982.
2. CONTROLLING DIMENSION: MILLIMETER.
3. DIMENSION A DOES NOT INCLUDE MOLD FLASH. PROTRUSIONS OR GATE BURRS. MOLD FLASH OR GATE BURRS SHALL NOT EXCEED 0.15 (0.006) PER SIDE.
4. DIMENSION B DOES NOT INCLUDE INTERLEAD FLASH OR PROTRUSION. INTERLEAD FLASH OR PROTRUSION SHALL NOT EXCEED 0.25 (0.010) PER SIDE.
5. TERMINAL NUMBERS ARE SHOWN FOR REFERENCE ONLY.
6. DIMENSION A AND B ARE TO BE DETERMINED AT DATUM PLANE -W-.

DIM	MILLIMETERS		INCHES	
	MIN	MAX	MIN	MAX
A	2.90	3.10	0.114	0.122
B	2.90	3.10	0.114	0.122
C	0.80	1.10	0.031	0.043
D	0.05	0.15	0.002	0.006
F	0.40	0.70	0.016	0.028
G	0.65 BSC		0.026 BSC	
K	0.25	0.40	0.010	0.016
L	4.90 BSC		0.193 BSC	
M	0°	6°	0°	6°